

HVM14

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0112-0400Z (Previous: ADE-208-082C) Rev.4.00 Oct.08.2003

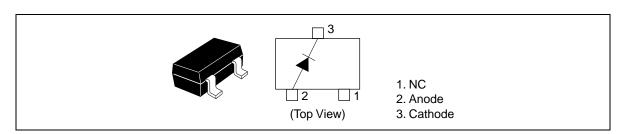
Features

- Low forward resistance. $(r_f = 7.0 \Omega \text{ max})$
- Low capacitance. (C = 0.25 pF typ)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVM14	H5	MPAK

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	50	V
Forward current	I _F	50	mA
Power dissipation	Pd	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

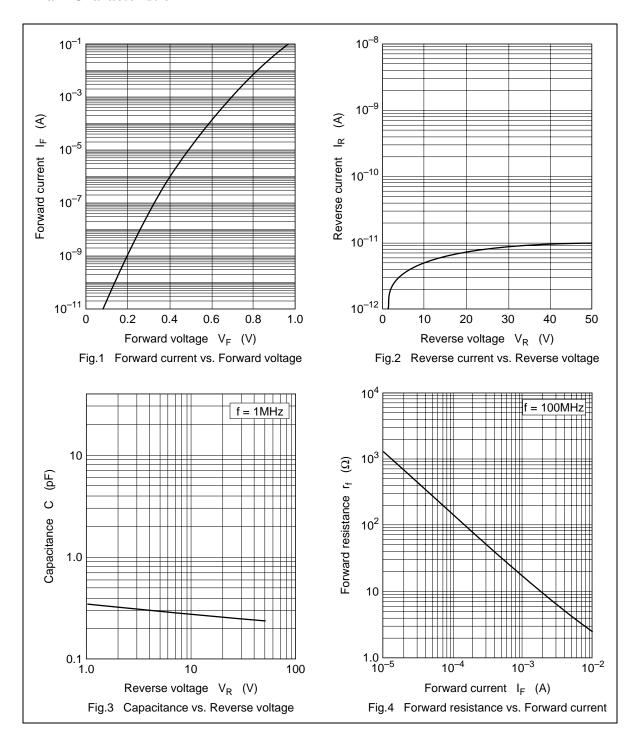
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

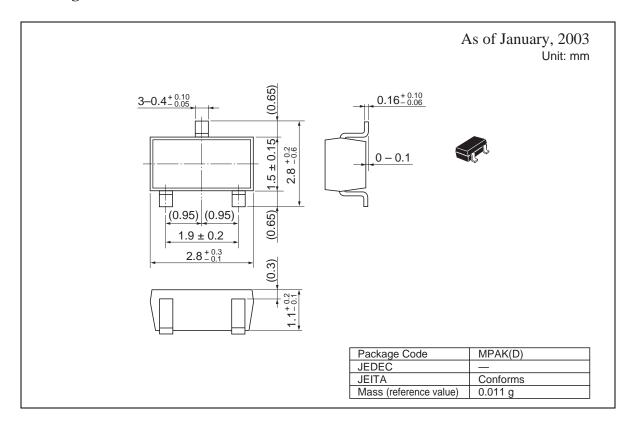
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	$V_{_{\rm F}}$	_	_	1.0	V	$I_F = 50 \text{ mA}$
Reverse current	I _R	_	_	100	nA	V _R = 50 V
Capacitance	С	_	0.25		pF	V _R = 50 V, f = 1 MHz
Forward resistance	r _f	_	_	7.0	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability *1	_	200	_	_	V	C = 200 pF, Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion; $I_R \ge 200 \text{ nA}$ at $V_R = 50 \text{ V}$

Main Characteristic



Package Dimensions



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